

APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claims 13-17 are canceled.

The claims are amended as follows:

1. (Twice amended) A multilayer-wiring substrate comprising:

a first wiring conductor with a recessed surface formed by etching a surface of the first wiring conductor,

a first insulating layer formed on a surface of the first wiring conductor except over the [recess] recessed surface so that a first via-hole penetrates through the first insulating layer to the recessed surface; and

a second insulating layer formed on the other surface of the first wiring conductor, wherein a depth of the [recess] recessed surface is 5-30% of the thickness of the wiring conductor, and said conductor comprises copper.

5. (Twice amended) A multilayer-wiring substrate comprising:

a first wiring conductor having top and bottom surfaces; a first insulating layer formed on the top surface of the first wiring conductor; a first via-hole penetrating through the first insulating layer; and a first columnar via-conductor formed in the via-hole,

wherein the first wiring conductor has a first recessed surface formed at the top surface of the first wiring conductor so that a bottom end of the first columnar via-conductor contacts the

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Appln. No. 09/471,332

first recessed surface of the first wiring conductor, a depth of the [recess] recessed surface is 5-30 % of the thickness of the wiring conductor, and said conductor comprises copper.

Claims 18-21 are added as new claims.